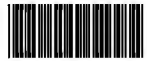


APPLICATION DATA SHEET

Electronic Version

Stylesheet Version v14.0

Title of Invention	METHOD FOR CREATING FLIP-CHIP CONDUCTIVE-POLYMER BUMPS USING PHOTOLITHOGRAPHY AND POLISHING		
Application Type : regular, Attorney Docket Number : 00131-00322-US1			
Correspondence address: Customer Number: 30678 			
Continuing Data: This is a Non-Provisional of US application number 60481196, filed 2003-08-08.			
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